

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

Claims 1-13. (cancelled)

Claim 14.(original) A method of manufacturing a thick film heater comprising a heating element applied directly to a surface of a target object, the method comprising the steps of: applying the heating element, comprising a thick film resistive circuit directly to the surface of the target object, wherein the thick film resistive circuit is made of a polymer-based ink; curing the heating element at a temperature in excess of 150.degree. C. for a period of time in excess of thirty minutes; and sealing the heating element with a dielectric layer.

Claim 15.(original) The method of claim 14 further comprising a plurality of said curing steps, wherein at least one of said curing steps occurs at a temperature in excess of 150.degree. C. for a period of time in excess of thirty minutes.

Claim 16. (original) The method of claim 14 further comprising the step of preparing the surface of the target object with a lower dielectric layer, and wherein the heating element in said applying layer is applied over the lower dielectric layer.

Claim 17. (original) The method of claim 14 wherein said curing step occurs at a temperature of 200.degree. C. or greater.

Claim 18. (original) The method of claim 14 wherein said curing step occurs for a period of two hours or longer.

Claim 19. (original) The method of claim 14 wherein the heating element is designed to operate at greater than 15 W/cm.sup.2.

Claim 20. (original) The method of claim 14 wherein the target object is non-ferrous.

Claim 21. (original) The method of claim 20 wherein the target object is aluminum.

Claim 22. (original) The method of claim 19 wherein the target object is copper.

Claim 23. (original) The method of claim 20 wherein the target object is ceramic.

Claim 24. (original) The method of claim 13 wherein the target object is high-expansion steel.

Claim 25. (original) The method of claim 13 wherein the polymer base of the thick film resistive circuit is an epoxy.

Claim 26. (original) The method of claim 24 wherein the polymer-based ink contains silver particles. (original)